
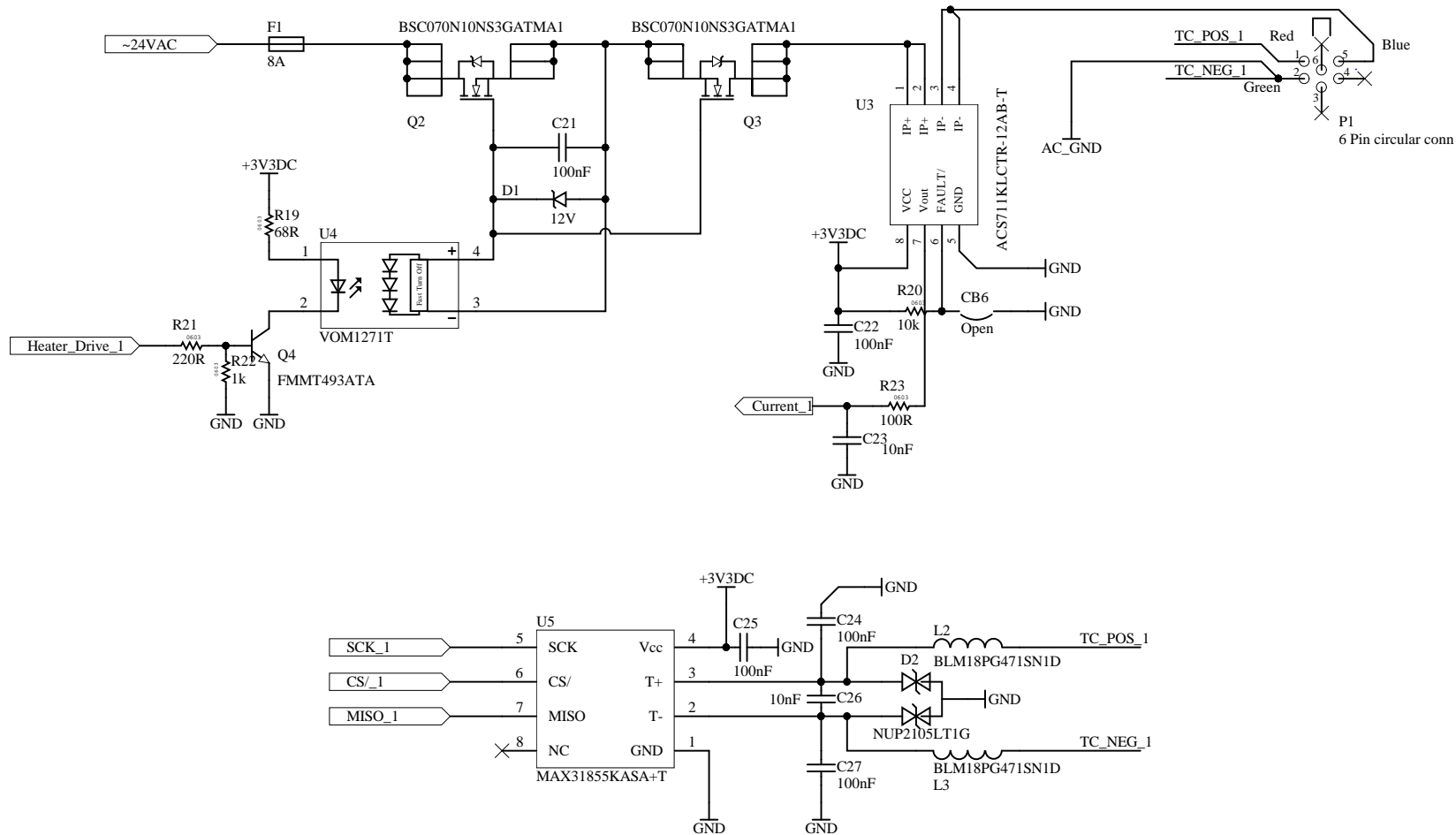



Title *			Kaumas Lithuania		
Size: Custom	Drawn By: Aurimas Vilkas	Revision: *			
Date: 5/16/2020 Time: 12:45:16 AM		Sheet * of *			
Author: Aurimas Vilkas		Engineer: Aurimas Vilkas	Project Name: *		

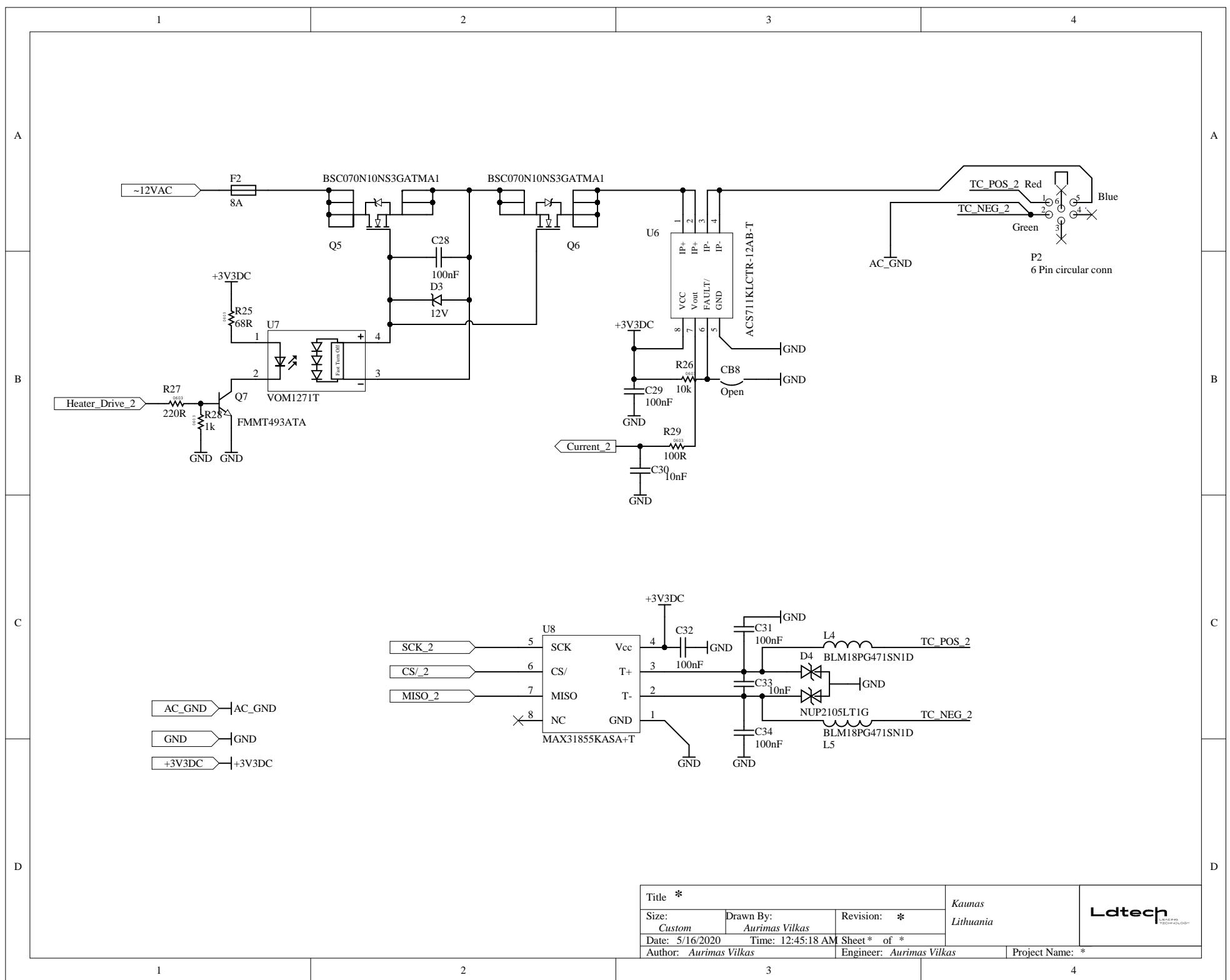



AC_GND AC_GND

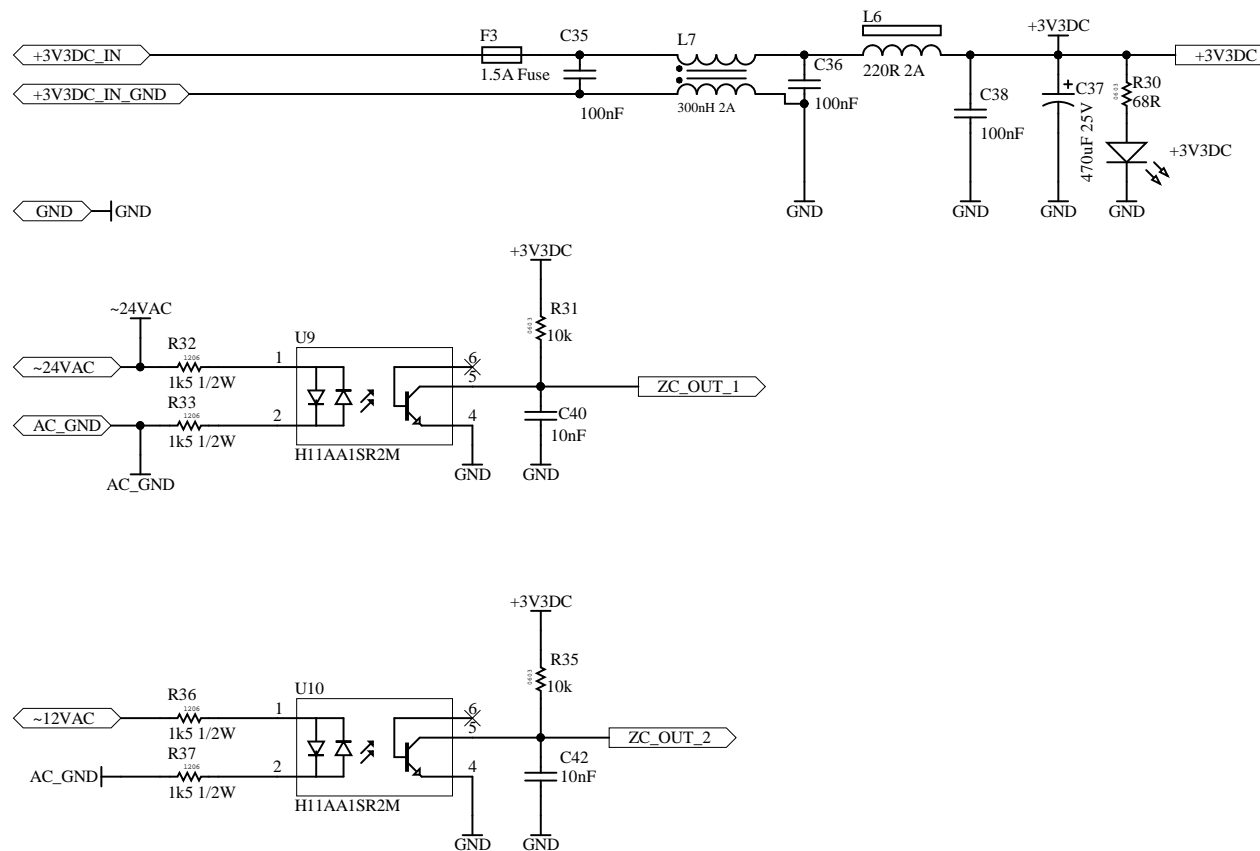
GND GND


+3V3DC +3V3DC

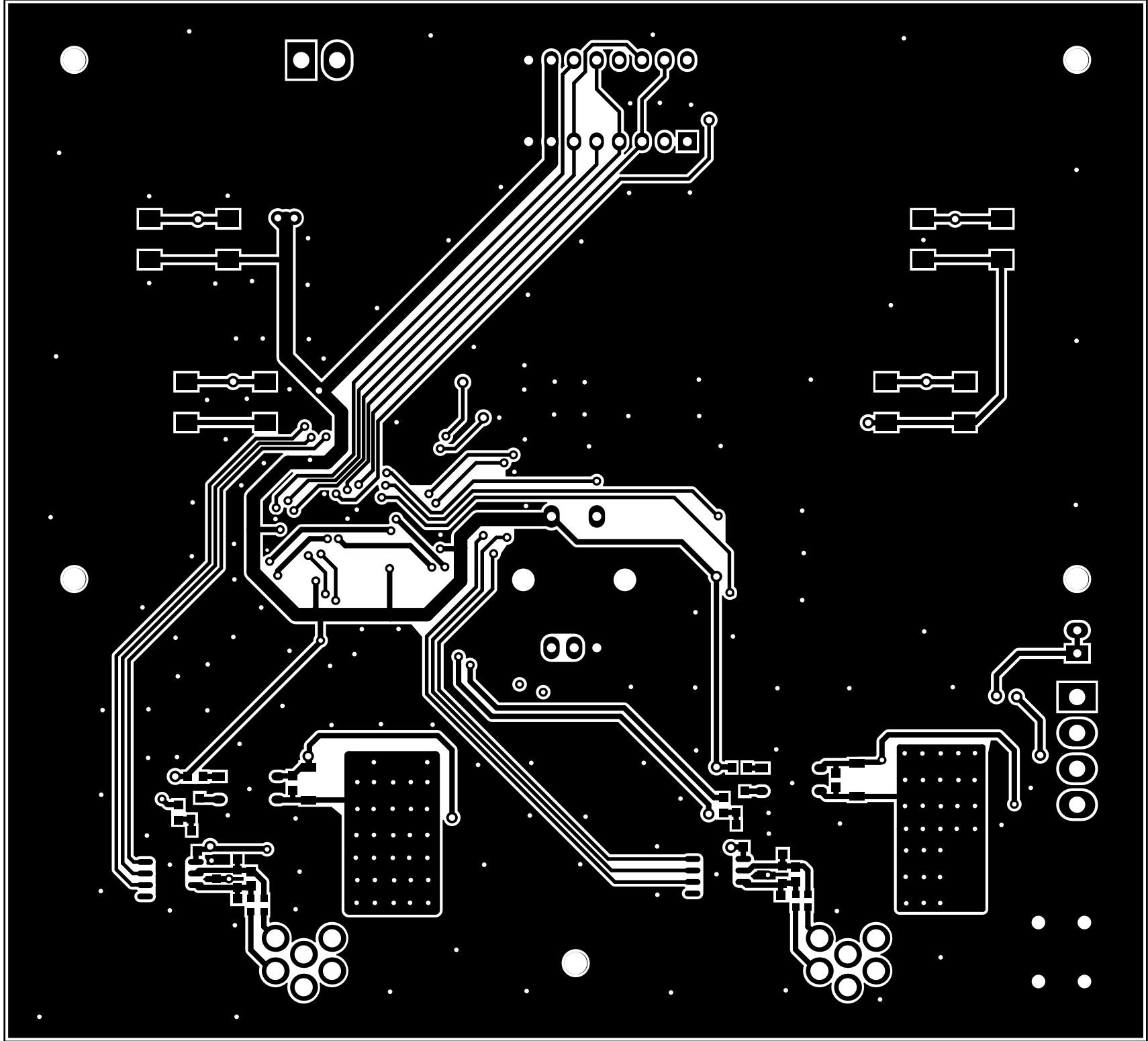
Title *			Kaunas Lithuania	
Size: Custom	Drawn By: Aurimas Vilkas	Revision: *		
Date: 5/16/2020	Time: 12:45:17 AM	Sheet * of *		
Author: Aurimas Vilkas		Engineer: Aurimas Vilkas	Project Name: *	

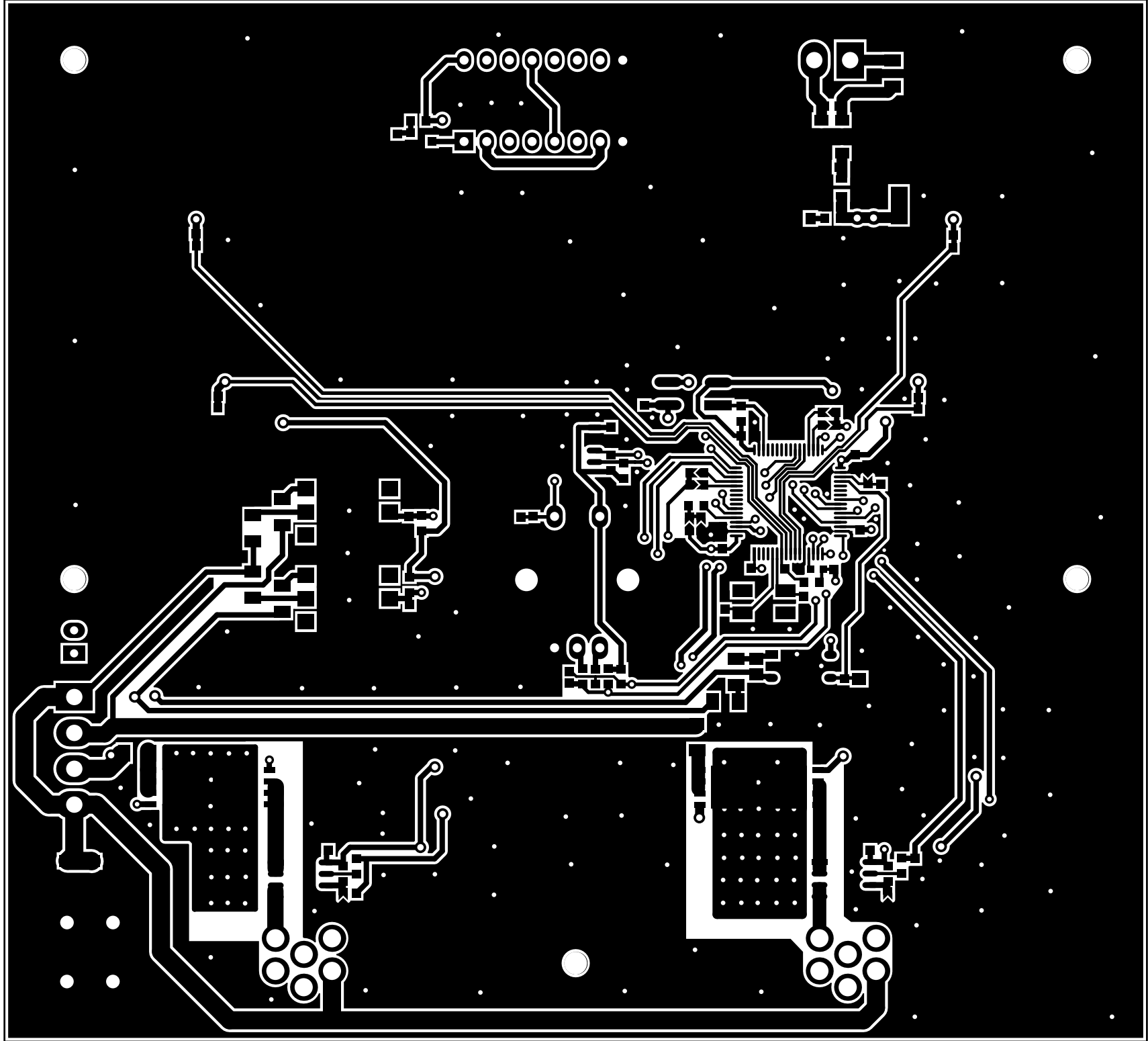


Title *			Kaunas Lithuania	
Size: Custom	Drawn By: Aurimas Vilkas	Revision: *		
Date: 5/16/2020	Time: 12:45:18 AM	Sheet * of *		
Author: Aurimas Vilkas		Engineer: Aurimas Vilkas	Project Name: *	



Title *			Kaunas Lithuania	
Size: Custom	Drawn By: Aurimas Vilkas	Revision: *		
Date: 5/16/2020	Time: 12:45:19 AM	Sheet * of *		
Author: Aurimas Vilkas		Engineer: Aurimas Vilkas	Project Name: *	





BTN_OK



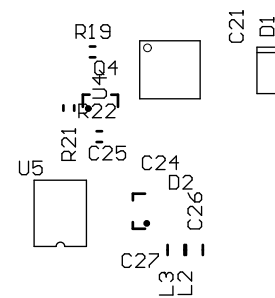
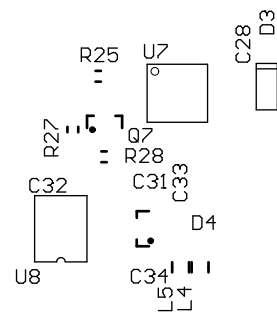
BTN_ON/OFF



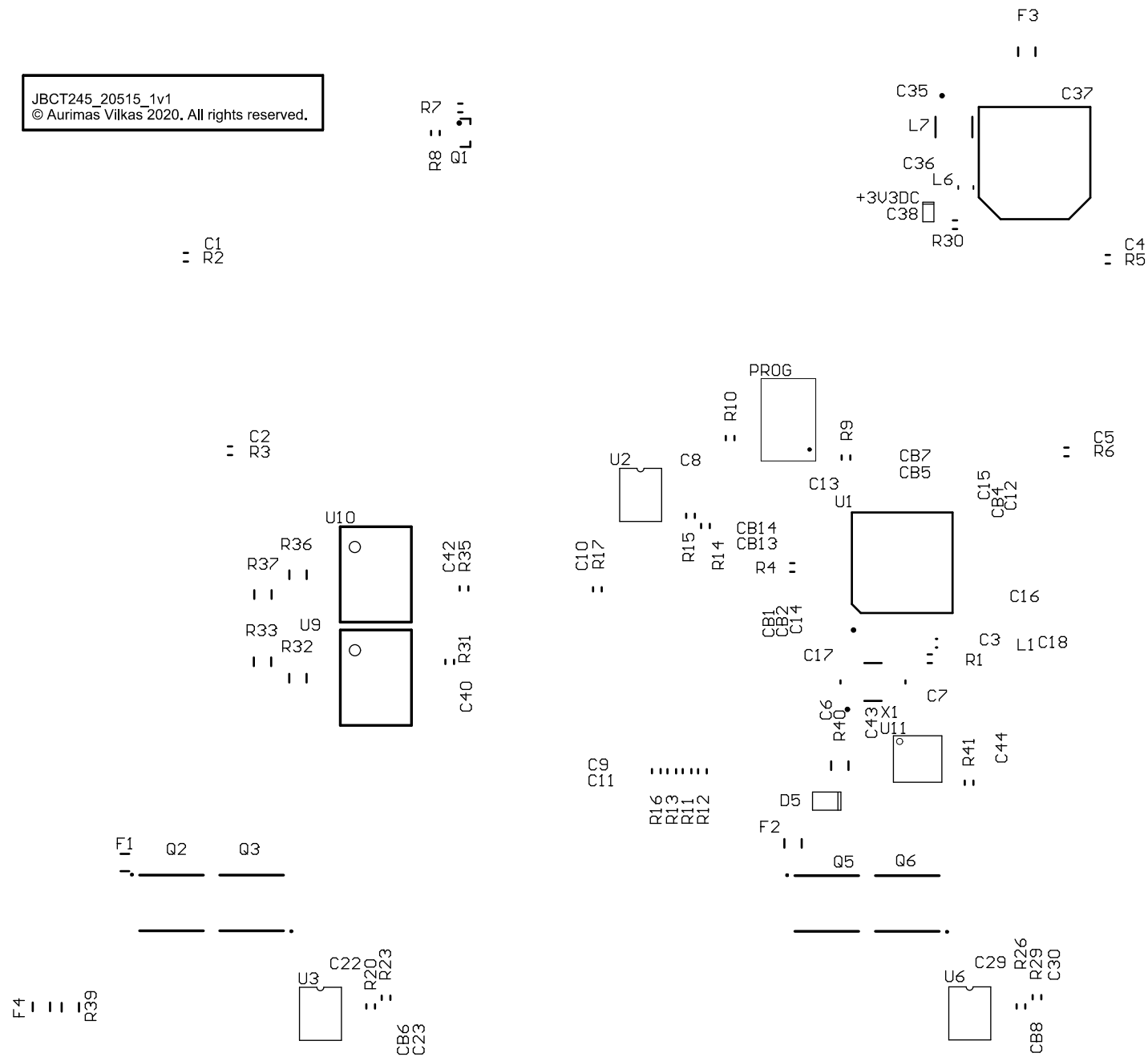
BTN_UP

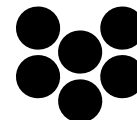
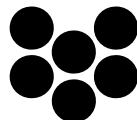
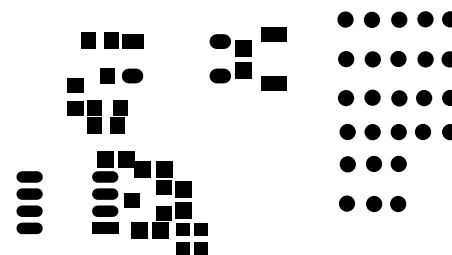
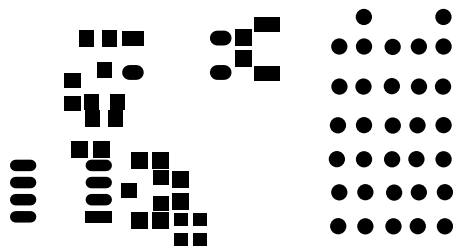
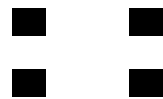
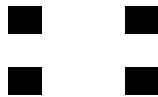


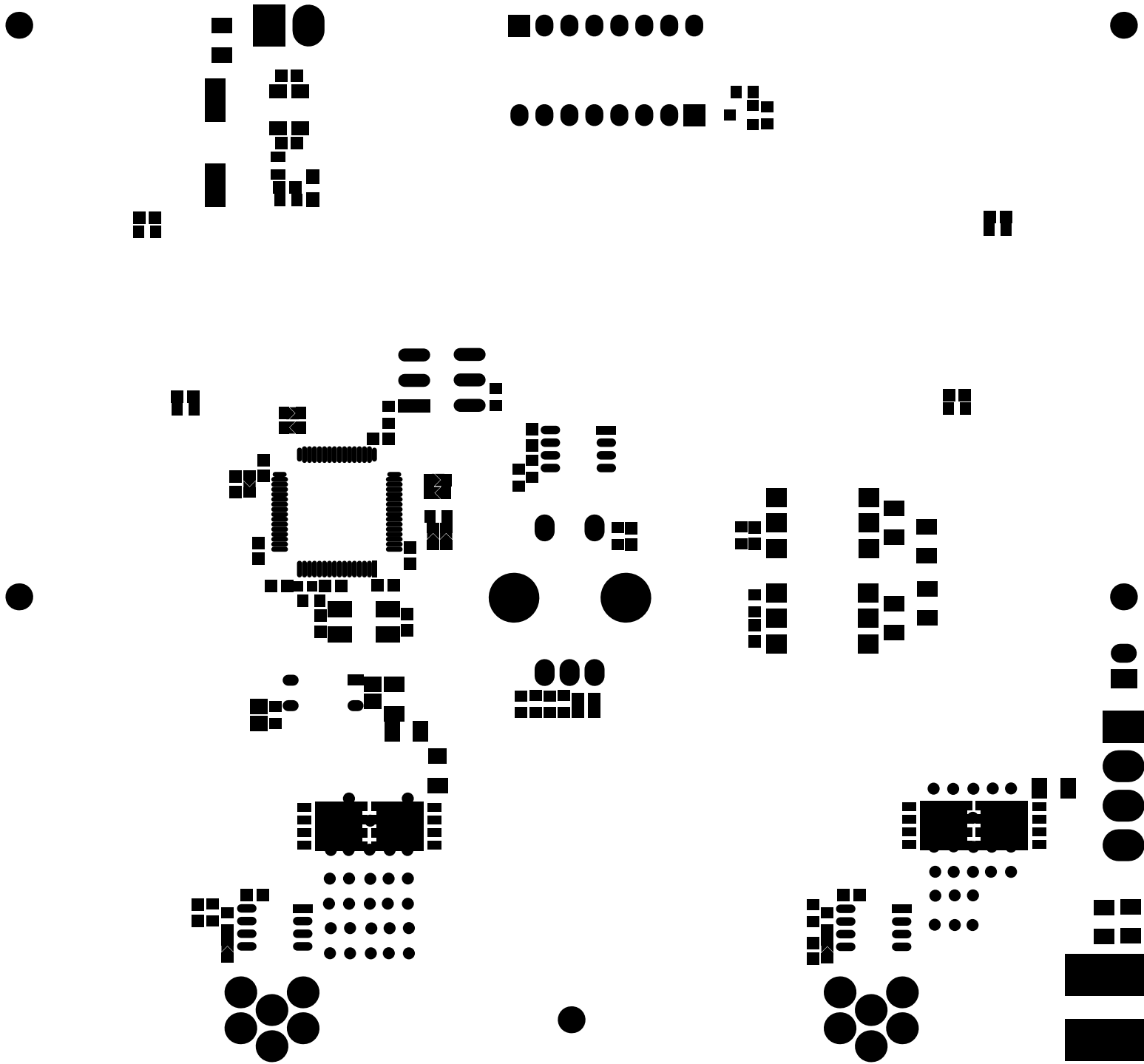
BTN_DN

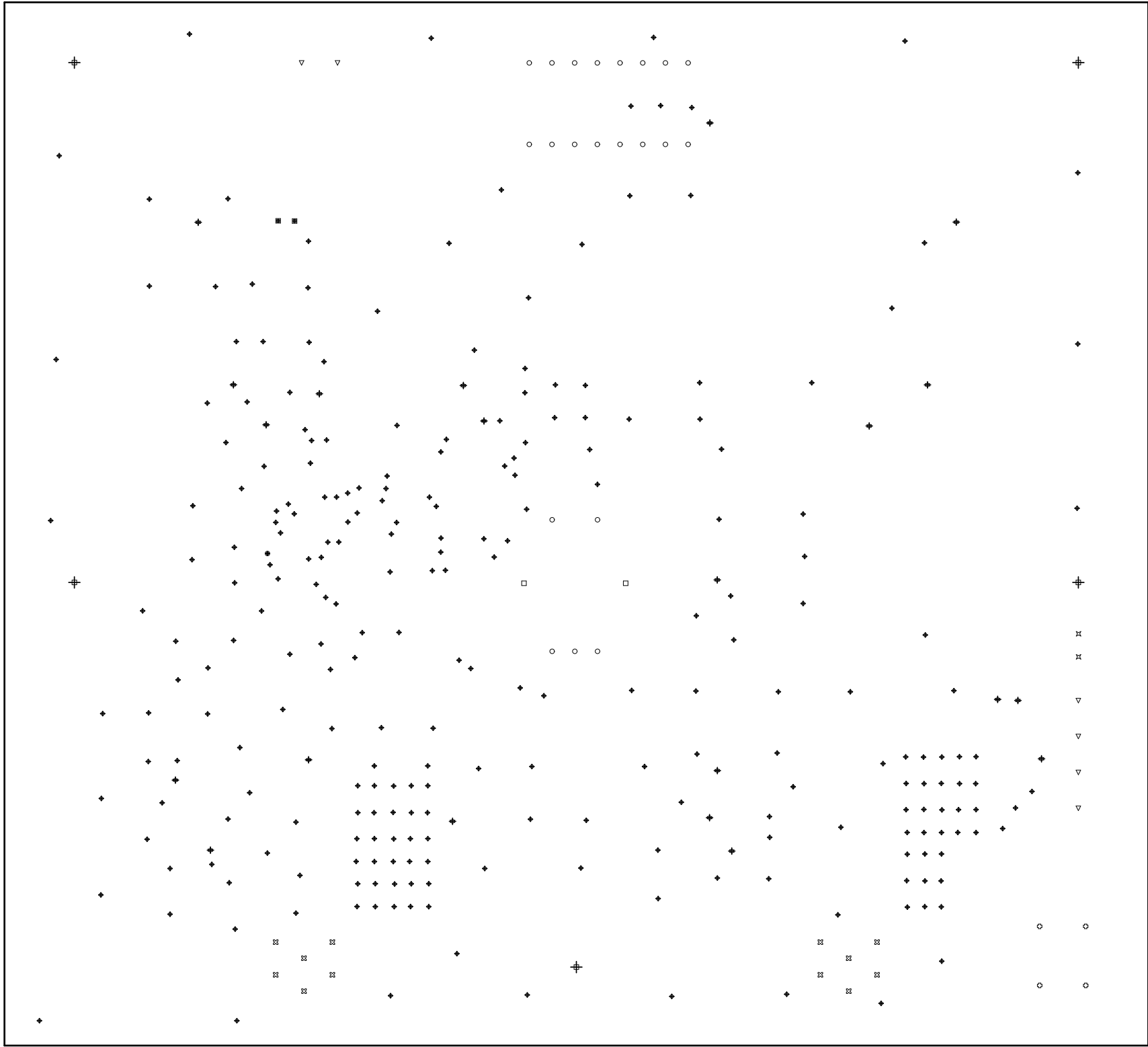


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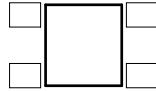




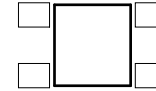




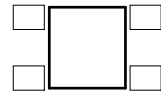
BTN_OK



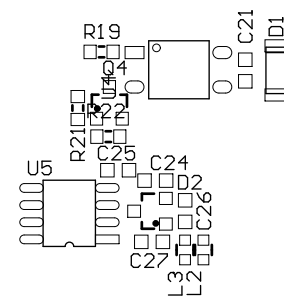
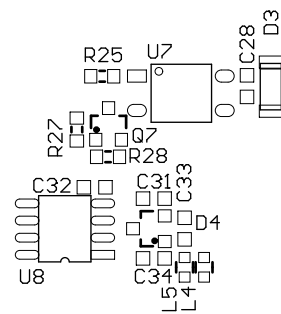
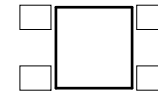
BTN_UP



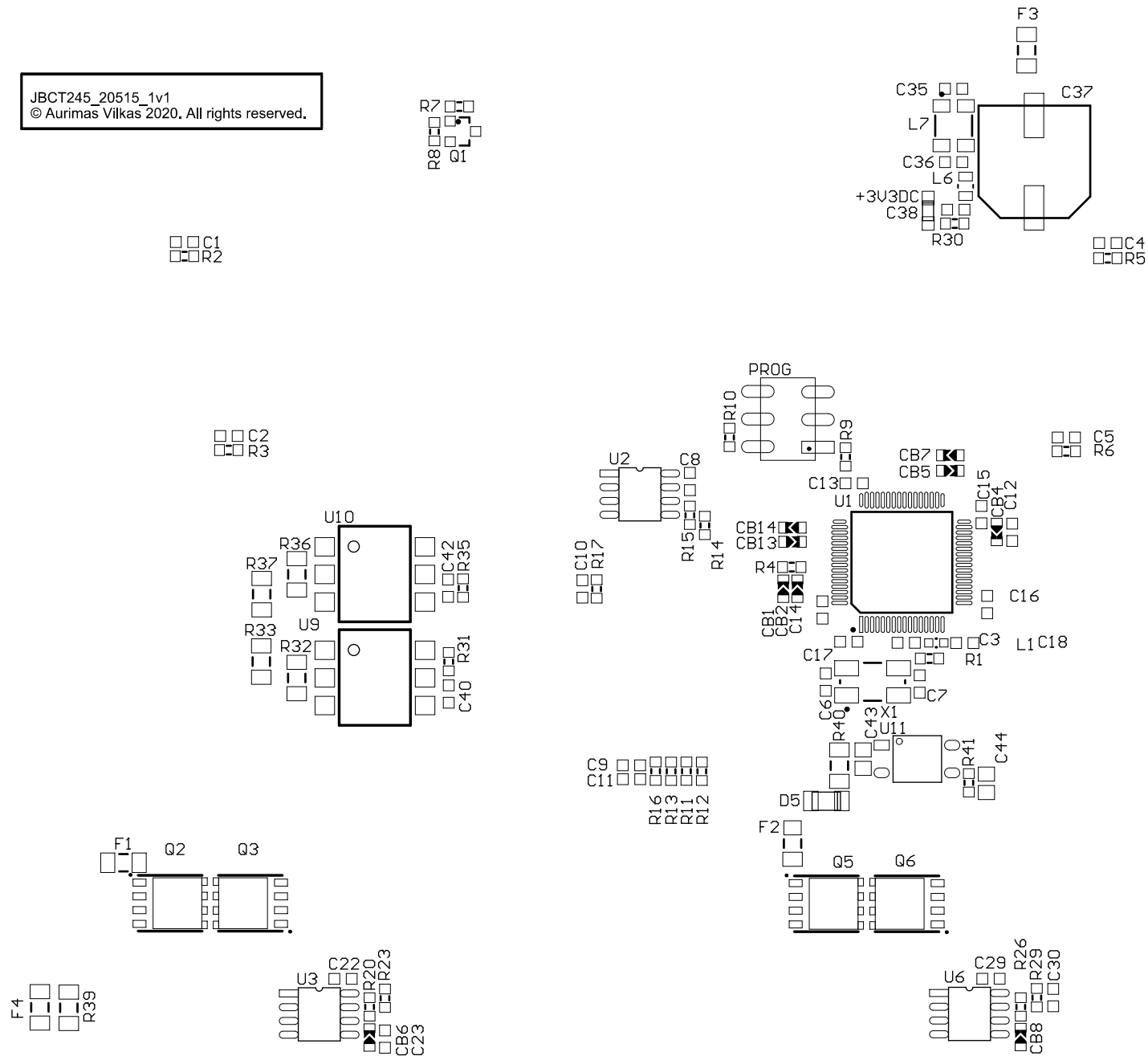
BTN_ON/OFF



BTN_DN



JBCT245_20515_1v1
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Quan tity	Comment	Description	Supplier Part Number 1	Footprint	Designator
1	1N4148W	1N4148W - Small Signal Diode, Single, 75 V, 150 mA, 1 V, 4 ns, 400 mA		2677464	SOD-123F
1	Sleep_Det	2 header, 2.54mm	Farnell	1248140	HDR1X2_2.54mm
1	24LC256-E/SN	24LC256-E/SN - EEPROM, 256 Kbit, 32K x 8bit, Serial I2C (2-Wire), 400 kHz, SOIC, 8 Pins	Farnell	1579573	SOIC-8
2	18p	0603N180J500CT - SMD Multilayer Ceramic Capacitor, 0603 [1608 Metric], 18 pF, 50 V, ± 5%, COG / NPO	Farnell	2496890	CAPC1608N
2	Blade Header	62409-1 - PCB Terminal, 6.35mm x 0.81mm, 0.25" x 0.032", Brass, 1.4 mm, Tin	Farnell	892609	Blade header
1	PROG	12A1050-3 - Board-To-Board Connector, 2.54 mm, 6 Contacts, Header, AMPMODU MOD II Series, Surface Mount, 2 Rows	Farnell	9689567	B6B_SMT
1	300nH 2A	744235900 - Filter, Line, Common Mode, 300 nH, WE-CNSW Series, 90 ohm, 2 A, 4.5mm x 3.2mm x 2.8mm	Farnell	2249865	1812_CM_WE
1	ACS711KLC1R-12AB-2 T	ACS711KLC1R-12AB-2 - Current Sensor, Overcurrent Fault, 4 mA, 100 kHz, SOIC, 8 Pins, 3 V, 5.5 V	Farnell	2057423	SOIC-8
1	ST7735 1.44inch	888-XH-A (LF) [SN] - Wire-To-Board Connector, Vertical, 2.5 mm, 8 Contacts, Header, XH Series, Through Hole, 1 Rows	Farnell	1516284	888-XH-A (LF) [SN]
1	ST7920 GLCD (128x64)	888-XH-A (LF) [SN] - Wire-To-Board Connector, Vertical, 2.5 mm, 8 Contacts, Header, XH Series, Through Hole, 1 Rows	Farnell	1516284	888-XH-A (LF) [SN]
1	BLM18A	BLM18AG6015N1D - Ferrite Bead, 0603 [1608 Metric], 600 ohm, 500 mA, BLM18A Series, 0.38 ohm, ± 25%	Farnell	1515679	0603L
4	BLM18PG4715N1D	BLM18PG4715N1D - Ferrite Bead, 0603 [1608 Metric], 470 ohm, 1 A, BLM18P Series, 0.2 ohm, ± 25%	Farnell	1515745	LL0603V2P
1	220R 2A	BLM21PG2215N1D - Ferrite Bead, 0805 [2012 Metric], 220 ohm, 2 A, BLM21P Series, 0.045 ohm, ± 25%	Farnell	1515661	LL0805V2P
4	BSC070N10NS3GAT4MA1	BSC070N10NS3GATMA1 - Power MOSFET, N Channel, 100 V, 90 A, 0.0063 ohm, TDSO N, Surface Mount	Farnell	2443421	PG-TDSO N-8
2	12V	BZT55C12-GS08 - Zener Single Diode, 12 V, 500 mW, SOD-80 (MiniMELF), 5 %, 2 Pins, 175 °C	Farnell	2690028	SOD-80C
3	Closed	Circuit Breaker			CB_0603
6	Open	Circuit Breaker			CB_0603
1	4u7F	CL10A475K08NNNC - SMD Multilayer Ceramic Capacitor, 4.7 µF, 6.3 V, 0603 [1608 Metric], ± 10%, X5R, CL Series	Farnell	3013399	CAPC1608N
2	1uF 50V	CL21B105K8FNNNC - SMD Multilayer Ceramic Capacitor, 1 µF, 50 V, 0805 [2012 Metric], ± 10%, X7R, CL Series	Farnell	3013482	CAPC2012N
1	HDR1X2	CONNECTOR, 2 way, HEADER, THT, 3.96MM, 10A, 250Vac	Farnell	9492003	HDR1X2_3M96V
1	HDR1X4	CONNECTOR, 4 way, HEADER, THT, 3.96MM, 10A, 250Vac	Farnell	9492020	HDR1X4_3M96V
1	10M	CRGCO120610M - SMD Chip Resistor, 1206 [3216 Metric], 10 Mohm, CRGCO Series, 200 V, Thick Film, 250 mW	Farnell	2861974	RESC3216N
3	1k	CRGH0603F1K0 - SMD Chip Resistor, 1 kohm, CRG Series, 50 V, Thick Film, 0603 [1608 Metric], 200 mW	Farnell	2332003	RESC1608N
3	220R	CRGH0603F220R - SMD Chip Resistor, 220 ohm, CRG Series, 50 V, Thick Film, 0603 [1608 Metric], 200 mW	Farnell	2331993	RESC1608N
1	8 MHz	CRYSTAL, 8M, 18PF, CL, 6X3.6MM SMT	Farnell	1611803	25MX-3SMXB
3	FMMT493ATA	FMMT493ATA - Bipolar (BJT) Single Transistor, NPN, 60 V, 150 MHz, 500 mW, 1 A, 300 HFE	Farnell	2061448	SOT23-3
4	Button	FSM2JRT - Tactile Switch, Non Illuminated, 24 V, 50 mA, 225 gf, PC Pin, FSM Series	Farnell	2610957	PB-6X6mm
2	H11AA1SR2M	H11AA1SR2M - Optocoupler, Transistor Output, 1 Channel, Surface Mount DIP, 6 Pins, 60 mA, 7.5 kV, 20 %	Farnell	2322525	SMDIP-6
1	Green LED	KPT-2012SGC - LED, Low Power, Green, SMD, 2mm x 1.25mm, 20 mA, 2.2 V, 568 nm	Farnell	2099239	LED_GRN
2	MAX31855KASA+T	MAX31855KASA+T - Temperature Sensor IC, Thermocouple, Digital, ± 2°C, - 200 °C, 1350 °C, NSOIC, 8 Pins	Farnell	2515622	SOIC-8
21	100nF	MC0805B104K250CT - SMD Multilayer Ceramic Capacitor, 0.1 µF, 25 V, 0805 [2012 Metric], ± 10%, X7R, MC Series	Farnell	1759166	CAPC1608N
2	1.5A Fuse	MCCFB12061FF/1.5 - Fuse, Surface Mount, 1.5 A, 32 V, Fast Acting, 1206	Farnell	1652166	1206F
2	8A	MCCFB12061FF/8 - Fuse, Surface Mount, 8 A, 32 V, Fast Acting, 1206	Farnell	2850026	1206F
2	100R	MCW0R03100T1000 - SMD Chip Resistor, High Voltage, 100 ohm, HVR Series, 200 V, Thick Film, 0603 [1608 Metric], 100 mW	Farnell	2825696	RESC1608N
3	68R	MCSR06x68R0FTL - SMD Chip Resistor, 68 ohm, MCSR 06 Series, 75 V, Ceramic, 0603 [1608 Metric], 100 mW	Farnell	2074301	RESC1608N
13	10nF	MCU0603R103KCT - SMD Multilayer Ceramic Capacitor, 10000 pF, 50 V, 0603 [1608 Metric], ± 10%, X7R, MCU Series	Farnell	9406182	CAPC1608N
1	470uF 25V	MCV7025M471GR3L - SMD Aluminium Electrolytic Capacitor, Radial Can - SMD, 470 µF, 25 V, VI, V-Chip Series	Farnell	2611378	10X10.5
5	1k5 1/2W	MCWF12P150FTL - SMD Chip Resistor, 1206 [3216 Metric], 1.5 kohm, MCWF12P Series, 200 V, Thick Film, 500 mW	Farnell	2694448	RESC3216N
18	10k	MCWR06x1002FTL - SMD Chip Resistor, 0603 [1608 Metric], 10 kohm, MCWR Series, 50 V, Thick Film, 100 mW	Farnell	2447230	RESC1608N
2	100k	MCWR06x1003FTL - SMD Chip Resistor, 0603 [1608 Metric], 100 kohm, MCWR Series, 50 V, Thick Film, 100 mW	Farnell	2447226RL	RESC1608N
2	NUP2105LT1G	NUP2105LT1G - TVS Diode, NUP21 Series, Bidirectional, 22 V, 40 V, SOT-23, 3 Pins	Farnell	2101833	SOT23-3
1	PEC11R-4225F-1 S0024	PEC11R-4225F-S0024 - Rotary Encoder, Mechanical, Incremental, 24 PPR, 24 Detents, Vertical, With Momentary Push Switch	Farnell	2381866	PEC12R-4XX0F-SX00X_1
2	6 Pin circular conn	RPC1-12RB-6P(71) - Circular Connector, RP Series, Panel Mount Receptacle, 6 Contacts, Solder Pin	Farnell	1077728	RPC1-12RB-6P(71)
1	STM32F446RCT6	STM32F446RCT6 - ARM MCU, High Performance, STM32 Family STM32F4 Series Microcontrollers, ARM Cortex-M4, 32bit	Farnell	2488309	LQFP-64N
1	TLP185SE	TLP185(GR-TPL)SE(T) - Optocoupler, 1 Channel, SOP, 4 Pins, 50 mA, 3.75 kV, 100 %	Farnell	3014097	SOP-4
2	VOM1271T	VOM1271T - Photovoltaic MOSFET Driver, Integrated Fast Turn-Off, Solid-State Relay 47µA Out, 24 µs Delay, SOP-4	Farnell	2395899	SOP-4

Design Rules Verification Report

Filename : C:\Users\Aurimas\OneDrive\Projects\JBCproject\JBCT245_1v1\T245_1v1.PcbD
oc

Warnings 4
Rule Violations 500

Warnings	
Zero hole size multi-layer pad(s) detected	2
Multilayer Pads with 0 size Hole found	2
Total	4

Rule Violations	
Clearance Constraint (Gap=0.3mm) (All),(All)	137
Short-Circuit Constraint (Allowed=No) (All),(All)	0
Un-Routed Net Constraint (All)	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=0.1mm) (Max=10mm) (Preferred=0.3mm) (All)	0
Hole Size Constraint (Min=0.025mm) (Max=2.54mm) (All)	0
Hole To Hole Clearance (Gap=0.254mm) (All),(All)	0
Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)	88
Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)	270
Silk to Silk (Clearance=0.254mm) (All),(All)	5
Net Antennae (Tolerance=0mm) (All)	0
Height Constraint (Min=0mm) (Max=50mm) (Preferred=12.7mm) (All)	0
Total	500

Zero hole size multi-layer pad(s) detected	
Pad Earth1-1(116.557mm,13.14mm) on Multi-Layer on Net GND	
Pad Earth2-1(116.565mm,6.63mm) on Multi-Layer on Net GND	

Multilayer Pads with 0 size Hole found	
Pad Earth1-1(116.557mm,13.14mm) on Multi-Layer	
Pad Earth2-1(116.565mm,6.63mm) on Multi-Layer	

Clearance Constraint (Gap=0.3mm) (All),(All)
Clearance Constraint: (0.25mm < 0.3mm) Between Track (61.56mm,95.78mm)(61.56mm,106.75mm) on Top Layer And Pad ST7920 GLCD
Clearance Constraint: (0.25mm < 0.3mm) Between Track (61.56mm,95.78mm)(61.56mm,106.75mm) on Top Layer And Pad ST7920 GLCD
Clearance Constraint: (0.25mm < 0.3mm) Between Track (64.06mm,107.04mm)(64.06mm,109.25mm) on Top Layer And Pad ST7735
Clearance Constraint: (0.25mm < 0.3mm) Between Track (64.06mm,107.04mm)(64.06mm,109.25mm) on Top Layer And Pad ST7735
Clearance Constraint: (0.2mm < 0.3mm) Between Track (82.59mm,19.38mm)(85.83mm,19.38mm) on Top Layer And Pad D2-3(83.48mm,18.43mm) on Top
Clearance Constraint: (0.2mm < 0.3mm) Between Track (21.455mm,18.9mm)(25.7mm,18.9mm) on Top Layer And Pad D4-3(23.35mm,17.95mm) on Top
Clearance Constraint: (0.2mm < 0.3mm) Between Track (21.395mm,17mm)(25.7mm,17mm) on Top Layer And Pad D4-3(23.35mm,17.95mm) on Top Layer
Clearance Constraint: (0.183mm < 0.3mm) Between Via (24.76mm,17.95mm) from Top Layer to Bottom Layer And Pad D4-2(25.7mm,18.9mm) on Top
Clearance Constraint: (0.183mm < 0.3mm) Between Via (24.76mm,17.95mm) from Top Layer to Bottom Layer And Pad D4-1(25.7mm,17mm) on Top Layer
Clearance Constraint: (0.292mm < 0.3mm) Between Region (0 hole(s)) Bottom Layer And Pad CB8-2(28.58mm,16.607mm) on Bottom Layer
Clearance Constraint: (0.24mm < 0.3mm) Between Track (27.105mm,18.545mm)(30.51mm,18.545mm) on Bottom Layer And Pad
Clearance Constraint: (0.21mm < 0.3mm) Between Track (27.105mm,18.545mm)(30.51mm,18.545mm) on Bottom Layer And Pad
Clearance Constraint: (0.28mm < 0.3mm) Between Pad C11-1(63.67mm,39.55mm) on Bottom Layer And Pad C9-1(63.68mm,40.83mm) on Bottom Layer
Clearance Constraint: (0.24mm < 0.3mm) Between Track (60.82mm,39.48mm)(60.82mm,40.29mm) on Bottom Layer And Pad R13-2(60.82mm,41.13mm)
Clearance Constraint: (0.24mm < 0.3mm) Between Track (58.79mm,40.29mm)(60.82mm,40.29mm) on Bottom Layer And Pad R13-2(60.82mm,41.13mm)
Clearance Constraint: (0.24mm < 0.3mm) Between Track (60.82mm,40.29mm)(62.93mm,40.29mm) on Bottom Layer And Pad R13-2(60.82mm,41.13mm)
Clearance Constraint: (0.295mm < 0.3mm) Between Track (61.6mm,38.56mm)(62.25mm,39.21mm) on Bottom Layer And Pad R13-1(60.82mm,39.43mm)
Clearance Constraint: (0.22mm < 0.3mm) Between Track (59.42mm,38.56mm)(61.6mm,38.56mm) on Bottom Layer And Pad R13-1(60.82mm,39.43mm) or
Clearance Constraint: (0.26mm < 0.3mm) Between Track (62.93mm,40.29mm)(63.47mm,40.83mm) on Bottom Layer And Pad R16-2(62.25mm,41.14mm)
Clearance Constraint: (0.25mm < 0.3mm) Between Track (60.82mm,40.29mm)(62.93mm,40.29mm) on Bottom Layer And Pad R16-2(62.25mm,41.14mm)
Clearance Constraint: (0.289mm < 0.3mm) Between Track (62.93mm,40.29mm)(63.47mm,40.83mm) on Bottom Layer And Pad R16-1(62.25mm,39.44mm)
Clearance Constraint: (0.25mm < 0.3mm) Between Track (60.82mm,40.29mm)(62.93mm,40.29mm) on Bottom Layer And Pad R16-1(62.25mm,39.44mm)
Clearance Constraint: (0.274mm < 0.3mm) Between Track (38.837mm,51.04mm)(39.937mm,52.14mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (40.787mm,49.97mm)(40.787mm,53.272mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (42.287mm,65.308mm)(42.287mm,69.097mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (31.767mm,61.57mm)(32.517mm,62.32mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (32.517mm,62.32mm)(33.799mm,62.32mm) on Bottom Layer And Pad
Clearance Constraint: (0.248mm < 0.3mm) Between Track (30.93mm,67.6mm)(33.32mm,65.21mm) on Bottom Layer And Pad C15-2(32.197mm,64.77mm)
Clearance Constraint: (0.241mm < 0.3mm) Between Track (37.787mm,52.69mm)(38.337mm,52.14mm) on Bottom Layer And Pad
Clearance Constraint: (0.241mm < 0.3mm) Between Track (37.787mm,52.69mm)(37.787mm,53.832mm) on Bottom Layer And Pad
Clearance Constraint: (0.28mm < 0.3mm) Between Pad R30-1(35.51mm,90.84mm) on Bottom Layer And Pad C38-1(35.36mm,92.12mm) on Bottom Layer
Clearance Constraint: (0.292mm < 0.3mm) Between Region (0 hole(s)) Bottom Layer And Pad CB7-2(35.927mm,69.45mm) on Bottom Layer
Clearance Constraint: (0.292mm < 0.3mm) Between Region (0 hole(s)) Bottom Layer And Pad CB5-2(34.213mm,68.02mm) on Bottom Layer
Clearance Constraint: (0.263mm < 0.3mm) Between Via (35.48mm,66.75mm) from Top Layer to Bottom Layer And Pad CB5-1(35.927mm,68.02mm) or
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-2(42.787mm,53.832mm) on Bottom Layer And Pad U1-1(43.287mm,53.832mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Track (43.287mm,52.25mm)(43.287mm,53.832mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-5(41.287mm,53.832mm) on Bottom Layer And Pad U1-4(41.787mm,53.832mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Track (41.287mm,50.05mm)(41.287mm,53.272mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-6(40.787mm,53.832mm) on Bottom Layer And Pad U1-5(41.287mm,53.832mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Track (40.787mm,49.97mm)(40.787mm,53.272mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-7(40.287mm,53.832mm) on Bottom Layer And Pad U1-6(40.787mm,53.832mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Track (40.287mm,53.832mm)(40.287mm,55.987mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (40.287mm,52.44mm)(40.287mm,53.832mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (41.287mm,50.05mm)(41.287mm,53.272mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (39.787mm,53.832mm)(39.787mm,56.127mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (40.787mm,49.97mm)(40.787mm,53.272mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-8(39.787mm,53.832mm) on Bottom Layer And Pad U1-7(40.287mm,53.832mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-9(39.287mm,53.832mm) on Bottom Layer And Pad U1-8(39.787mm,53.832mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Track (39.287mm,53.832mm)(39.287mm,56.257mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (40.287mm,53.832mm)(40.287mm,55.987mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (40.287mm,52.44mm)(40.287mm,53.832mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-10(38.787mm,53.832mm) on Bottom Layer And Pad U1-9(39.287mm,53.832mm) on Bottom

Clearance Constraint (Gap=0.3mm) (All),(All)
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-26(33.799mm,60.32mm) on Bottom Layer And Pad U1-25(33.799mm,59.82mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Track (31.4mm,59.82mm)(33.799mm,59.82mm) on Bottom Layer And Pad U1-26(33.799mm,60.32mm)
Clearance Constraint: (0.2mm < 0.3mm) Between Track (32.88mm,61.82mm)(33.799mm,61.82mm) on Bottom Layer And Pad U1-28(33.799mm,61.32mm)
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-29(33.799mm,61.82mm) on Bottom Layer And Pad U1-28(33.799mm,61.32mm) on Bottom Layer
Clearance Constraint: (0.288mm < 0.3mm) Between Track (31.64mm,60.58mm)(32.88mm,61.82mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-30(33.799mm,62.32mm) on Bottom Layer And Pad U1-29(33.799mm,61.82mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Track (32.517mm,62.32mm)(33.799mm,62.32mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (32.88mm,61.82mm)(33.799mm,61.82mm) on Bottom Layer And Pad U1-30(33.799mm,62.32mm)
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-31(33.799mm,62.82mm) on Bottom Layer And Pad U1-30(33.799mm,62.32mm) on Bottom Layer
Clearance Constraint: (0.2mm < 0.3mm) Between Track (32.327mm,62.82mm)(33.799mm,62.82mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-32(33.799mm,63.32mm) on Bottom Layer And Pad U1-31(33.799mm,62.82mm) on Bottom Layer
Clearance Constraint: (0.23mm < 0.3mm) Between Track (33.799mm,63.5mm)(33.799mm,64.101mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (32.517mm,62.32mm)(33.799mm,62.32mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (32.327mm,62.82mm)(33.799mm,62.82mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (36.287mm,65.308mm)(36.287mm,66.583mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-34(36.287mm,65.308mm) on Bottom Layer And Pad U1-33(35.787mm,65.308mm) on Bottom
Clearance Constraint: (0.2mm < 0.3mm) Between Track (36.787mm,65.308mm)(36.787mm,67.523mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-35(36.787mm,65.308mm) on Bottom Layer And Pad U1-34(36.287mm,65.308mm) on Bottom
Clearance Constraint: (0.2mm < 0.3mm) Between Track (35.432mm,65.308mm)(35.787mm,65.308mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (37.287mm,65.308mm)(37.287mm,68.793mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (36.287mm,65.308mm)(36.287mm,66.583mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-36(37.287mm,65.308mm) on Bottom Layer And Pad U1-35(36.787mm,65.308mm) on Bottom
Clearance Constraint: (0.2mm < 0.3mm) Between Track (36.787mm,65.308mm)(36.787mm,67.523mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (37.787mm,64.103mm)(37.787mm,65.308mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-37(37.787mm,65.308mm) on Bottom Layer And Pad U1-36(37.287mm,65.308mm) on Bottom
Clearance Constraint: (0.2mm < 0.3mm) Between Track (38.287mm,64.233mm)(38.287mm,65.308mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (37.287mm,65.308mm)(37.287mm,68.793mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-38(38.287mm,65.308mm) on Bottom Layer And Pad U1-37(37.787mm,65.308mm) on Bottom
Clearance Constraint: (0.2mm < 0.3mm) Between Track (38.787mm,64.413mm)(38.787mm,65.308mm) on Bottom Layer And Pad
Clearance Constraint: (0.287mm < 0.3mm) Between Track (38.787mm,64.413mm)(39.16mm,64.04mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Pad U1-39(38.787mm,65.308mm) on Bottom Layer And Pad U1-38(38.287mm,65.308mm) on Bottom
Clearance Constraint: (0.2mm < 0.3mm) Between Track (37.787mm,64.103mm)(37.787mm,65.308mm) on Bottom Layer And Pad
Clearance Constraint: (0.2mm < 0.3mm) Between Track (38.287mm,64.233mm)(38.287mm,65.308mm) on Bottom Layer And Pad

Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.167mm < 0.254mm) Between Pad D2-2(85.83mm,19.38mm) on Top Layer And Pad C24-1(85.85mm,20.7mm)
Minimum Solder Mask Sliver Constraint: (0.167mm < 0.254mm) Between Pad D2-1(85.83mm,17.48mm) on Top Layer And Pad C27-2(85.61mm,16.16mm)
Minimum Solder Mask Sliver Constraint: (0.152mm < 0.254mm) Between Pad Q4-2(82.6mm,25.29mm) on Top Layer And Pad R22-1(82.42mm,23.96mm)
Minimum Solder Mask Sliver Constraint: (0.152mm < 0.254mm) Between Pad Q4-1(80.7mm,25.29mm) on Top Layer And Pad R22-2(80.72mm,23.96mm)
Minimum Solder Mask Sliver Constraint: (0.237mm < 0.254mm) Between Pad R19-1(81.92mm,30.24mm) on Top Layer And Pad U4-1(83.51mm,30.19mm)
Minimum Solder Mask Sliver Constraint: (0.237mm < 0.254mm) Between Pad R21-2(79.31mm,25.23mm) on Top Layer And Pad Q4-1(80.7mm,25.29mm)
Minimum Solder Mask Sliver Constraint: (0.252mm < 0.254mm) Between Pad D2-2(85.83mm,19.38mm) on Top Layer And Pad C26-1(87.26mm,19.24mm)
Minimum Solder Mask Sliver Constraint: (0.252mm < 0.254mm) Between Pad D2-1(85.83mm,17.48mm) on Top Layer And Pad C26-2(87.26mm,17.64mm)
Minimum Solder Mask Sliver Constraint: (0.217mm < 0.254mm) Between Pad C32-2(19.71mm,21.02mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.167mm < 0.254mm) Between Pad C32-1(21.31mm,21.02mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.207mm < 0.254mm) Between Pad C28-2(31.79mm,29.32mm) on Top Layer And Pad D3-1(33.55mm,30.3mm)
Minimum Solder Mask Sliver Constraint: (0.207mm < 0.254mm) Between Pad C28-1(31.79mm,27.72mm) on Top Layer And Pad D3-2(33.55mm,26.66mm)
Minimum Solder Mask Sliver Constraint: (0.247mm < 0.254mm) Between Pad U7-4(30.14mm,29.265mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.247mm < 0.254mm) Between Pad Q7-1(20.59mm,24.54mm) on Top Layer And Pad R27-2(19.19mm,24.45mm)
Minimum Solder Mask Sliver Constraint: (0.082mm < 0.254mm) Between Pad Q7-2(22.49mm,24.54mm) on Top Layer And Pad R28-1(22.35mm,23.28mm)
Minimum Solder Mask Sliver Constraint: (0.082mm < 0.254mm) Between Pad Q7-1(20.59mm,24.54mm) on Top Layer And Pad R28-2(20.65mm,23.28mm)
Minimum Solder Mask Sliver Constraint: (0.127mm < 0.254mm) Between Pad C31-1(25.69mm,20.18mm) on Top Layer And Pad D4-2(25.7mm,18.9mm) or
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad C34-2(25.69mm,15.75mm) on Top Layer And Pad D4-1(25.7mm,17mm) or
Minimum Solder Mask Sliver Constraint: (0.013mm < 0.254mm) Between Pad R26-2(28.57mm,17.68mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.089mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB8-2(28.58mm,16.607mm) or
Minimum Solder Mask Sliver Constraint: (0.051mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB8-1(28.58mm,14.893mm) or
Minimum Solder Mask Sliver Constraint: (0.051mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB8-1(28.58mm,14.893mm) or
Minimum Solder Mask Sliver Constraint: (0.187mm < 0.254mm) Between Pad R31-1(81.33mm,49.55mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.177mm < 0.254mm) Between Pad R35-1(80.01mm,58.04mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.177mm < 0.254mm) Between Pad R35-2(80.01mm,56.34mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.057mm < 0.254mm) Between Pad D5-1(45.07mm,37.54mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.137mm < 0.254mm) Between Pad U11-3(34.9mm,40.14mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.167mm < 0.254mm) Between Pad C44-1(31.74mm,40.02mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.167mm < 0.254mm) Between Pad C44-2(31.74mm,38.32mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R17-2(67.69mm,57.96mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.107mm < 0.254mm) Between Pad R17-1(67.69mm,56.26mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.077mm < 0.254mm) Between Pad C11-1(63.67mm,39.55mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.227mm < 0.254mm) Between Pad R16-2(62.25mm,41.14mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.077mm < 0.254mm) Between Pad C11-2(65.27mm,39.55mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.217mm < 0.254mm) Between Pad R11-2(59.41mm,41.14mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.217mm < 0.254mm) Between Pad R11-1(59.41mm,39.44mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.207mm < 0.254mm) Between Pad R11-2(59.41mm,41.14mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.227mm < 0.254mm) Between Pad R16-2(62.25mm,41.14mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.207mm < 0.254mm) Between Pad R11-1(59.41mm,39.44mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.227mm < 0.254mm) Between Pad R16-1(62.25mm,39.44mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.217mm < 0.254mm) Between Pad C11-1(63.67mm,39.55mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.195mm < 0.254mm) Between Pad L1-1(37.059mm,52.13mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.251mm < 0.254mm) Between Pad U1-11(38.287mm,53.832mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.251mm < 0.254mm) Between Pad U1-10(38.787mm,53.832mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.247mm < 0.254mm) Between Pad R1-1(37.84mm,50.69mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.251mm < 0.254mm) Between Pad U1-12(37.787mm,53.832mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.254mm < 0.254mm) Between Pad U1-9(39.287mm,53.832mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.251mm < 0.254mm) Between Pad U1-7(40.287mm,53.832mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.251mm < 0.254mm) Between Pad U1-8(39.787mm,53.832mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.249mm < 0.254mm) Between Pad U1-48(43.287mm,65.308mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.111mm < 0.254mm) Between Pad U1-47(42.787mm,65.308mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.188mm < 0.254mm) Between Pad U1-46(42.287mm,65.308mm) on Bottom Layer And Pac

Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.199mm < 0.254mm) Between Pad CB4-1(30.787mm,63.227mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.161mm < 0.254mm) Between Pad U1-31(33.799mm,62.82mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.23mm < 0.254mm) Between Pad U1-30(33.799mm,62.32mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.199mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad C15-1(32.197mm,63.17mm) on Bottom
Minimum Solder Mask Sliver Constraint: (0.199mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad C15-1(32.197mm,63.17mm) on Bottom
Minimum Solder Mask Sliver Constraint: (0.04mm < 0.254mm) Between Pad C18-2(34.537mm,52.12mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.244mm < 0.254mm) Between Pad X1-3(39.837mm,49.79mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad R3-2(102.47mm,69.93mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad R3-1(100.77mm,69.93mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad R2-2(104.85mm,87.83mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.254mm) Between Pad R2-1(106.55mm,87.83mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.197mm < 0.254mm) Between Pad Q1-1(81.2mm,100.29mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.227mm < 0.254mm) Between Pad L6-1(33.66mm,95.18mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.157mm < 0.254mm) Between Pad C38-2(33.76mm,92.12mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.077mm < 0.254mm) Between Pad R30-1(35.51mm,90.84mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.077mm < 0.254mm) Between Pad R30-2(33.81mm,90.84mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.197mm < 0.254mm) Between Pad C4-1(21.34mm,89.04mm) on Bottom Layer And Pad R5-2(21.4mm,87.64mm)
Minimum Solder Mask Sliver Constraint: (0.197mm < 0.254mm) Between Pad C4-2(19.74mm,89.04mm) on Bottom Layer And Pad R5-1(19.7mm,87.64mm)
Minimum Solder Mask Sliver Constraint: (0.067mm < 0.254mm) Between Pad R6-2(25.22mm,69.82mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.067mm < 0.254mm) Between Pad R6-1(23.52mm,69.82mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.211mm < 0.254mm) Between Pad CB5-1(35.927mm,68.02mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.089mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB7-2(35.927mm,69.45mm) or
Minimum Solder Mask Sliver Constraint: (0.217mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB7-2(35.927mm,69.45mm) or
Minimum Solder Mask Sliver Constraint: (0.211mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB7-2(35.927mm,69.45mm) or
Minimum Solder Mask Sliver Constraint: (0.211mm < 0.254mm) Between Pad CB5-2(34.213mm,68.02mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.211mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB7-1(34.213mm,69.45mm) or
Minimum Solder Mask Sliver Constraint: (0.051mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB7-1(34.213mm,69.45mm) or
Minimum Solder Mask Sliver Constraint: (0.051mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB7-1(34.213mm,69.45mm) or
Minimum Solder Mask Sliver Constraint: (0.211mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB5-2(34.213mm,68.02mm) or
Minimum Solder Mask Sliver Constraint: (0.217mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB5-2(34.213mm,68.02mm) or
Minimum Solder Mask Sliver Constraint: (0.089mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB5-2(34.213mm,68.02mm) or
Minimum Solder Mask Sliver Constraint: (0.051mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB5-1(35.927mm,68.02mm) or
Minimum Solder Mask Sliver Constraint: (0.051mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB5-1(35.927mm,68.02mm) or
Minimum Solder Mask Sliver Constraint: (0.211mm < 0.254mm) Between Region (0 hole(s)) Bottom Solder And Pad CB5-1(35.927mm,68.02mm) or
Minimum Solder Mask Sliver Constraint: (0.151mm < 0.254mm) Between Pad C17-2(43.63mm,52.24mm) on Bottom Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.218mm < 0.254mm) Between Pad C17-2(43.63mm,52.24mm) on Bottom Layer And Pac

Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)

Silk To Solder Mask Clearance Constraint: (0.025mm < 0.254mm) Between Arc (80.75mm,26.04mm) on Top Overlay And Pad Q4-1(80.7mm,25.29mm) or
Silk To Solder Mask Clearance Constraint: (0.025mm < 0.254mm) Between Arc (85.08mm,17.53mm) on Top Overlay And Pad D2-1(85.83mm,17.48mm)
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Arc (92.995mm,9.625mm) on Top Overlay And Pad L3-1(87.25mm,14.835mm)
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Arc (92.995mm,9.625mm) on Top Overlay And Pad L2-1(88.61mm,16.285mm)
Silk To Solder Mask Clearance Constraint: (0.121mm < 0.254mm) Between Arc (92.995mm,9.625mm) on Top Overlay And Pad L2-2(88.61mm,14.835mm)
Silk To Solder Mask Clearance Constraint: (0.025mm < 0.254mm) Between Arc (20.64mm,25.29mm) on Top Overlay And Pad Q7-1(20.59mm,24.54mm)
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Arc (32.995mm,9.625mm) on Top Overlay And Pad L4-1(28.61mm,15.815mm)
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Arc (32.995mm,9.625mm) on Top Overlay And Pad L5-1(27.17mm,14.365mm)
Silk To Solder Mask Clearance Constraint: (0.025mm < 0.254mm) Between Arc (24.95mm,17.05mm) on Top Overlay And Pad D4-1(25.7mm,17mm) or
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Arc (35.86mm,102.77mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Arc (35.86mm,102.77mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.025mm < 0.254mm) Between Arc (80.45mm,100.24mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Arc (48.097mm,70.045mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.1mm < 0.254mm) Between Arc (110.689mm,30.718mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (117.05mm,41.58mm)(117.05mm,46.66mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (119.59mm,41.58mm)(119.59mm,46.66mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (117.05mm,41.58mm)(117.05mm,46.66mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Track (119.59mm,41.58mm)(119.59mm,46.66mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.162mm < 0.254mm) Between Text "L2" (88.4mm,12.26mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.141mm < 0.254mm) Between Track (69.03mm,44.26mm)(69.03mm,48.36mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.141mm < 0.254mm) Between Track (69.03mm,53.56mm)(69.03mm,57.66mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.141mm < 0.254mm) Between Track (56.63mm,44.26mm)(56.63mm,48.36mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.141mm < 0.254mm) Between Track (56.63mm,53.56mm)(56.63mm,57.66mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.22mm < 0.254mm) Between Text "C25" (80.84mm,22.24mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.22mm < 0.254mm) Between Text "C25" (80.84mm,22.24mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.235mm < 0.254mm) Between Track (87.875mm,15.56mm)(87.875mm,15.935mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (87.985mm,15.56mm)(87.985mm,15.935mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (89.235mm,15.56mm)(89.235mm,15.935mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.235mm < 0.254mm) Between Track (87.875mm,15.185mm)(87.875mm,15.56mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (87.985mm,15.185mm)(87.985mm,15.56mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (89.235mm,15.185mm)(89.235mm,15.56mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (86.625mm,15.185mm)(86.625mm,15.56mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (87.875mm,15.185mm)(87.875mm,15.56mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.235mm < 0.254mm) Between Track (87.985mm,15.185mm)(87.985mm,15.56mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (86.625mm,15.56mm)(86.625mm,15.935mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.125mm < 0.254mm) Between Track (87.875mm,15.56mm)(87.875mm,15.935mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.235mm < 0.254mm) Between Track (87.985mm,15.56mm)(87.985mm,15.935mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (108.471mm,85.55mm)(108.471mm,91.55mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (102.832mm,85.55mm)(108.471mm,85.55mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (108.471mm,85.55mm)(108.471mm,91.55mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (102.832mm,91.55mm)(108.471mm,91.55mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (27.231mm,67.58mm)(27.231mm,73.58mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (21.592mm,67.58mm)(27.231mm,67.58mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (27.231mm,67.58mm)(27.231mm,73.58mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (21.592mm,73.58mm)(27.231mm,73.58mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (23.181mm,85.55mm)(23.181mm,91.55mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (17.542mm,85.55mm)(23.181mm,85.55mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (23.181mm,85.55mm)(23.181mm,91.55mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (17.542mm,91.55mm)(23.181mm,91.55mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (104.431mm,67.58mm)(104.431mm,73.58mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (98.792mm,67.58mm)(104.431mm,67.58mm) on Top Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.244mm < 0.254mm) Between Track (104.431mm,67.58mm)(104.431mm,73.58mm) on Top Overlay And Pac

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[illegible]

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Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)

Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(34.887mm,64.22mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(34.887mm,64.22mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(34.887mm,64.22mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(34.887mm,64.22mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,54.92mm)(34.887mm,64.22mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,64.22mm)(44.187mm,64.22mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,64.22mm)(44.187mm,64.22mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,64.22mm)(44.187mm,64.22mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,64.22mm)(44.187mm,64.22mm) on Bottom Overlay And Pac
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Track (34.887mm,64.22mm)(44.187mm,64.22mm) on Bottom Overlay And Pac

Silk to Silk (Clearance=0.254mm) (All),(All)

Silk To Silk Clearance Constraint: (Collision < 0.254mm) Between Text "R22" (80.061mm,25.364mm) on Top Overlay And Arc (80.75mm,26.04mm) on Top
Silk To Silk Clearance Constraint: (Collision < 0.254mm) Between Text "L3" (87.02mm,12.22mm) on Top Overlay And Arc (92.995mm,9.625mm) on Top
Silk To Silk Clearance Constraint: (Collision < 0.254mm) Between Text "L5" (26.52mm,11.88mm) on Top Overlay And Arc (32.995mm,9.625mm) on Top
Silk To Silk Clearance Constraint: (0.094mm < 0.254mm) Between Text "R40" (44.84mm,43.19mm) on Bottom Overlay And Arc (44.599mm,46.006mm) or
Silk To Silk Clearance Constraint: (0.252mm < 0.254mm) Between Text "U3" (95.22mm,20.63mm) on Bottom Overlay And Arc (93.28mm,20.3mm) or